

Indium3.2HF Water-Soluble Solder Paste for Fine Feature SiP Application

- Exceptional printing for small aperture with Type 5 and 6 powder sizes
- Long stencil life
- Good response-to-pause
- Outstanding slump resistance
- Superior fine-pitch soldering ability

Major Users

- Front-end-modules in all leading mobile phones

>2,000,000,000
SiP packages built



Contact our engineers: askus@indium.com

Learn more: www.indium.com

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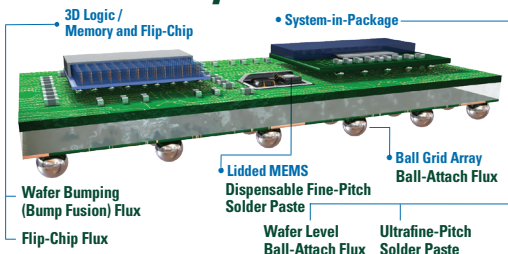
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Heterogeneous Integration & Assembly Materials



Material Type	Material Name	Flux Type	Comments
Flip-Chip Flux	WS-446	WS	Best flux for poor solderability, halogen-containing
	WS-446HF	WS	Best all-around halogen-free flip-chip flux, easily cleaned
	NC-26-A	ULR, NC	Best compatibility with CUF/MUF
	NC-26S	ULR, NC	Avoids capillary flow up to die surface for fine-pitch devices
Ball-Attach Flux	WS-446-AL	WS	Best flux for poor solderability, halogen-containing
	WS-575-C	WS	Eliminates the prefluxing step for OSP
	WS-823	WS	Best all-around halogen-free ball-attach flux, easily cleaned
	WS-676	WS	For printing on wafer, suitable for WL CSP
	WS-759	WS	For printing on wafer and panel, suitable for FOW/PLP
SiP Solder Paste	Indium3.2HF	WS	Type 6-SG solder paste suitable for ultrafine-pitch printing, designed for 01005 and smaller discrete devices
	Indium8.9HF	Solvent clean, NC	
	SMQ@75	ULR, NC	

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